

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of :
Daisuke SAKURAI et al. : **Attn: APPLICATION BRANCH**
Serial No. NEW : Attorney Docket No. 2003_1517A
Filed October 28, 2003 : **THE COMMISSIONER IS AUTHORIZED
TO CHARGE ANY DEFICIENCY IN THE
FEES FOR THIS PAPER TO DEPOSIT
ACCOUNT NO. 23-0975**
MANUFACTURING METHOD FOR ELECTRONIC
COMPONENT-MOUNTED COMPONENT,
MANUFACTURING METHOD FOR ELECTRONIC
COMPONENT-MOUNTED COMPLETED
PRODUCT WITH THE ELECTRONIC
COMPONENT-METHOD COMPONENT,
AND ELECTRONIC COMPONENT-MOUNTED
COMPLETED PRODUCT

**COVER LETTER FOR APPLICATION FILED
WITHOUT EXECUTED DECLARATION**

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

The above-identified application has been submitted without an executed oath or declaration pursuant to 37 CFR 1.41(c).

It is respectfully requested that this application be assigned a serial number and awarded a filing date pursuant to 37 CFR 1.53.

A duly executed oath or declaration pursuant to 37 CFR 1.63 will be submitted after notification by the U.S. Patent and Trademark Office pursuant to 37 CFR 1.53(f).


A non-executed copy of the Declaration and Power of Attorney, containing the inventorship information, is attached. It is respectfully requested that all communications be directed to the firm indicated on the attached Declaration and Power of Attorney, namely:

WENDEROTH, LIND & PONACK, L.L.P.
2033 K Street, N.W., Suite 800
Washington, D.C. 20006-1021

The required U.S. Patent and Trademark Office Filing Fee is submitted herewith.

Respectfully submitted,

Daisuke SAKURAI et al.

By 
Michael S. Huppert
Registration No. 40,268
Attorney for Applicants

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October 28, 2003

DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

(X) Original () Supplemental () Substitute () PCT () DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: MANUFACTURING METHOD FOR ELECTRONIC COMPONENT-MOUNTED COMPONENT, MANUFACTURING METHOD FOR ELECTRONIC COMPONENT-MOUNTED COMPLETED PRODUCT WITH THE ELECTRONIC COMPONENT-METHOD COMPONENT, AND ELECTRONIC COMPONENT-MOUNTED COMPLETED PRODUCT

of which is described and claimed in:

() the attached specification, or

(X) the specification in application Serial No. _____, filed October 28, 2003, and with amendments through _____, or

() the specification in International Application No. _____, filed _____, and as amended on _____ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2002-316022	October 30, 2002	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; and Jeffrey R. Filipek, Reg. No. 41,471, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents

associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from AOYAMA & PARTNERS as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Direct Correspondence to: <div style="text-align: center; margin-top: 20px;"> CUSTOMER NO. 000513 </div>		Direct Telephone Calls to: <div style="text-align: center; margin-top: 20px;"> WENDEROTH, LIND & PONACK, L.L.P. 2033 "K" Street, N.W., Suite 800 Washington, D.C. 20006-1021 Phone: (202) 721-8200 Fax: (202) 721-8250 </div>	
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Post Office Address	ADDRESS	CITY	STATE OR COUNTRY ZIP CODE

Full Name of Fifth Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
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Full Name of Sixth Inventor	FAMILY NAME	FIRST GIVEN NAME	SECOND GIVEN NAME
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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor _____ Date _____
Daisuke SAKURAI
2nd Inventor _____ Date _____
Norihiro TSUKAHARA
3rd Inventor _____ Date _____
4th Inventor _____ Date _____
5th Inventor _____ Date _____
6th Inventor _____ Date _____

The above application may be more particularly identified as follows:

U.S. Application Serial No. _____ Filing Date October 28, 2003

Applicant Reference Number 538578 Atty Docket No. 2003 1517A

Title of Invention MANUFACTURING METHOD FOR ELECTRONIC COMPONENT-MOUNTED COMPONENT, MANUFACTURING METHOD FOR ELECTRONIC COMPONENT-MOUNTED COMPLETED PRODUCT WITH THE ELECTRONIC COMPONENT-METHOD COMPONENT, AND ELECTRONIC COMPONENT-MOUNTED COMPLETED PRODUCT